

# Engineering the Ideal Array



**Mark Rosker**  
**Microsystem Technology Symposium**  
**5 March 2007**

## Report Documentation Page

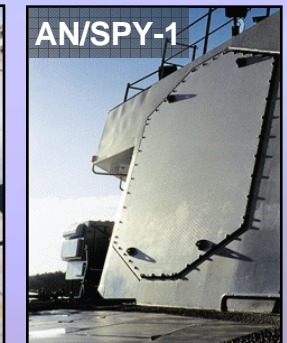
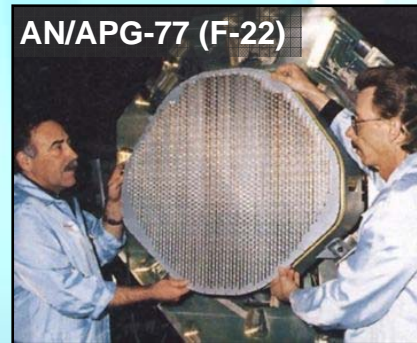
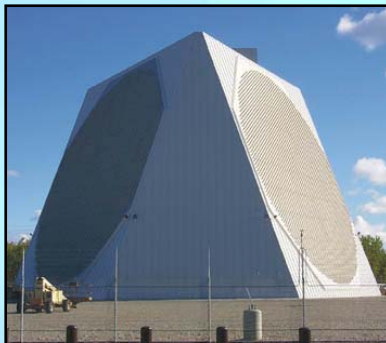
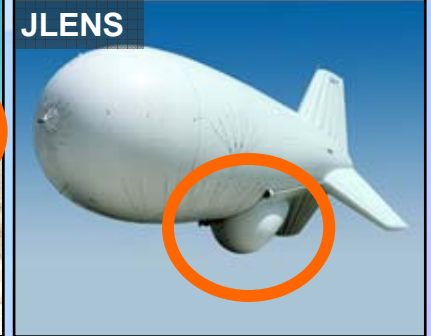
*Form Approved*  
*OMB No. 0704-0188*

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1. REPORT DATE <b>05 MAR 2007</b>	2. REPORT TYPE <b>N/A</b>	3. DATES COVERED <b>-</b>	
4. TITLE AND SUBTITLE <b>Engineering the Ideal Array</b>		5a. CONTRACT NUMBER	
		5b. GRANT NUMBER	
		5c. PROGRAM ELEMENT NUMBER	
6. AUTHOR(S)		5d. PROJECT NUMBER	
		5e. TASK NUMBER	
		5f. WORK UNIT NUMBER	
7. PERFORMING ORGANIZATION NAME(S) AND ADDRESS(ES) <b>DARPA</b>		8. PERFORMING ORGANIZATION REPORT NUMBER	
9. SPONSORING/MONITORING AGENCY NAME(S) AND ADDRESS(ES)		10. SPONSOR/MONITOR'S ACRONYM(S)	
		11. SPONSOR/MONITOR'S REPORT NUMBER(S)	
12. DISTRIBUTION/AVAILABILITY STATEMENT <b>Approved for public release, distribution unlimited</b>			
13. SUPPLEMENTARY NOTES <b>DARPA Microsystems Technology Symposium held in San Jose, California on March 5-7, 2007. Presentations, The original document contains color images.</b>			
14. ABSTRACT			
15. SUBJECT TERMS			
16. SECURITY CLASSIFICATION OF:			17. LIMITATION OF ABSTRACT
a. REPORT <b>unclassified</b>	b. ABSTRACT <b>unclassified</b>	c. THIS PAGE <b>unclassified</b>	<b>UU</b>
			18. NUMBER OF PAGES <b>16</b>
			19a. NAME OF RESPONSIBLE PERSON



# RF Arrays in Military Systems



**Arrays are the heart of sensor systems for many military platforms**

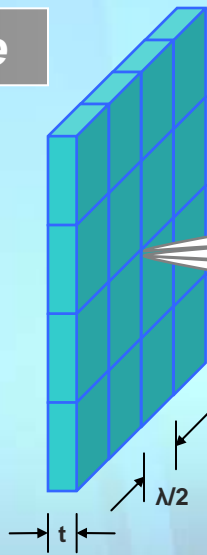


# Ideal Array: The Vision



## Architecture

- Scalable
- Reconfigurable
- Embedded thermal management
- Negligible mass
- Wafer-thin
- Dirt cheap



## Transmit

- Huge transmit power available
- Enormous bandwidth
- Near-unity power added efficiency

## Beamsteering

- Precise phase & amplitude control of each element
- Near-instantaneous speed
- Suppressed sidebands

## Receive

- Near-zero noise figure
- Enormous dynamic range
- Minimal power dissipation

*All we need now is a bit of technology...*

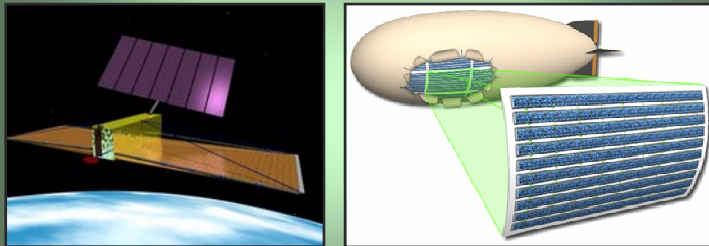




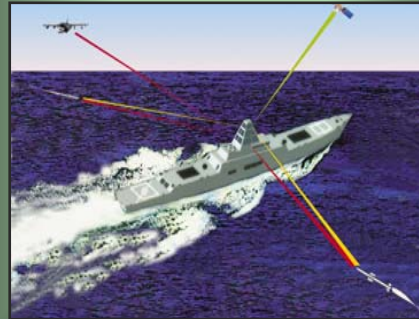
# What Does it Enable?



## Massive Sensor Arrays



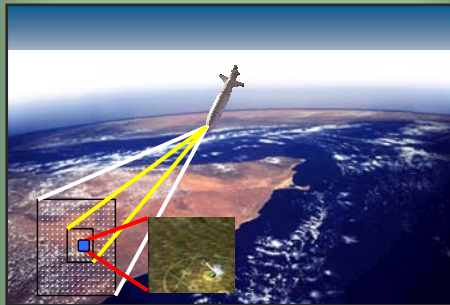
## Multi-function Systems



## Conformal Sensors



## Frequency Agile Sensors



## Greater Range



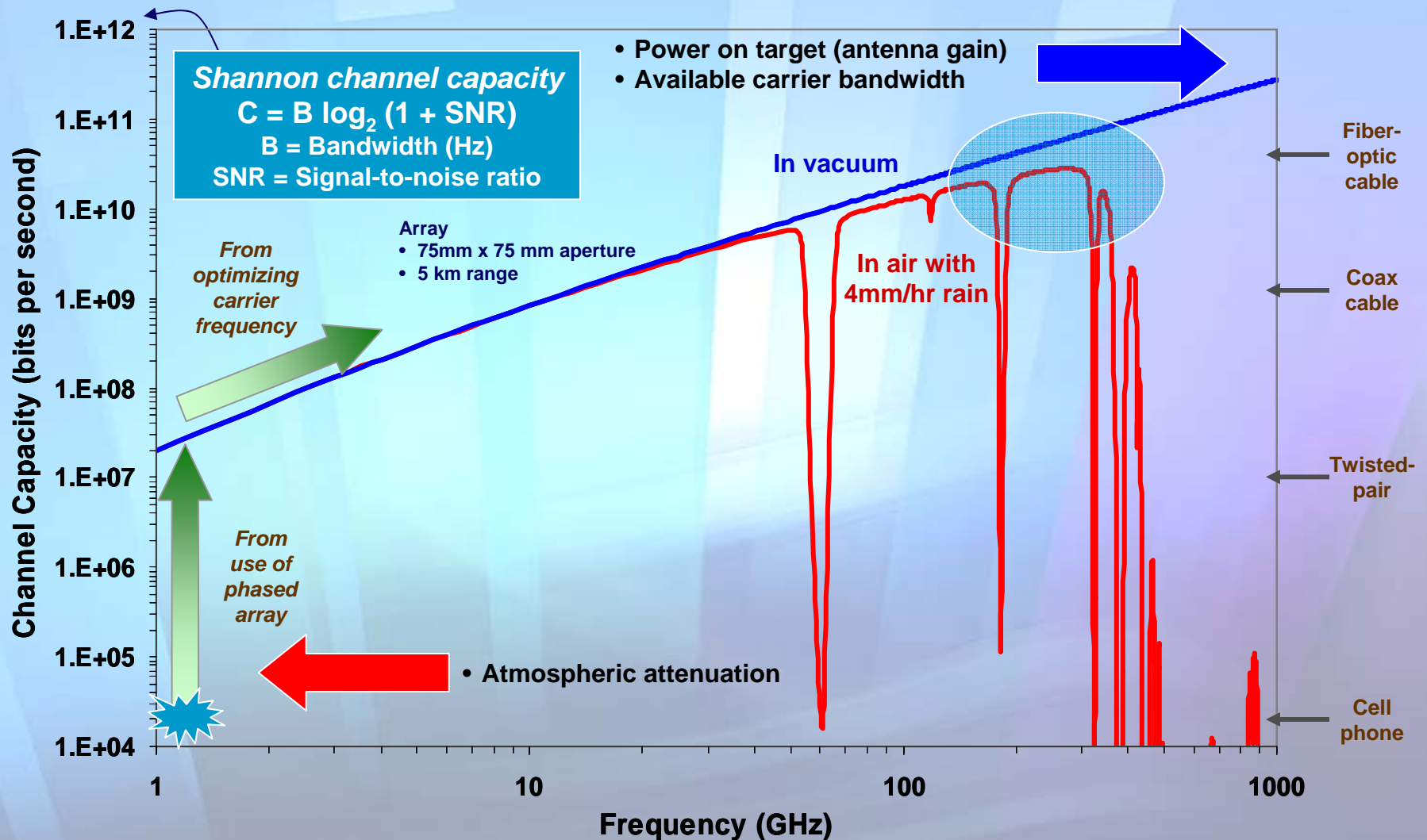
## Reduced System Size



**Compact, robust, intelligent sensor and communications systems**



# The Ideal Array and Frequency



**For many applications, the ideal array is a millimeter-wave array**



# Arrays in Military Systems



THAAD



XBR



AN/MPO Sentinel



JLENS



AN/SP



Which of these are millimeter-wave arrays?

AN/TPO-37



AN/APG-81 (JSEF)



JSTARS



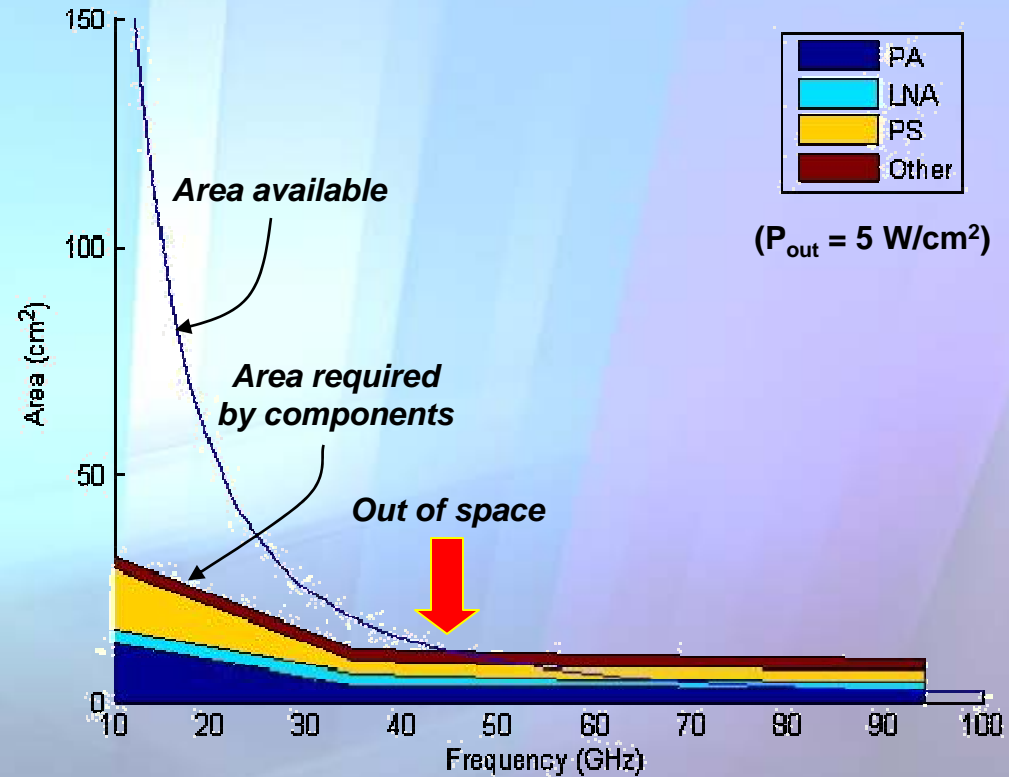
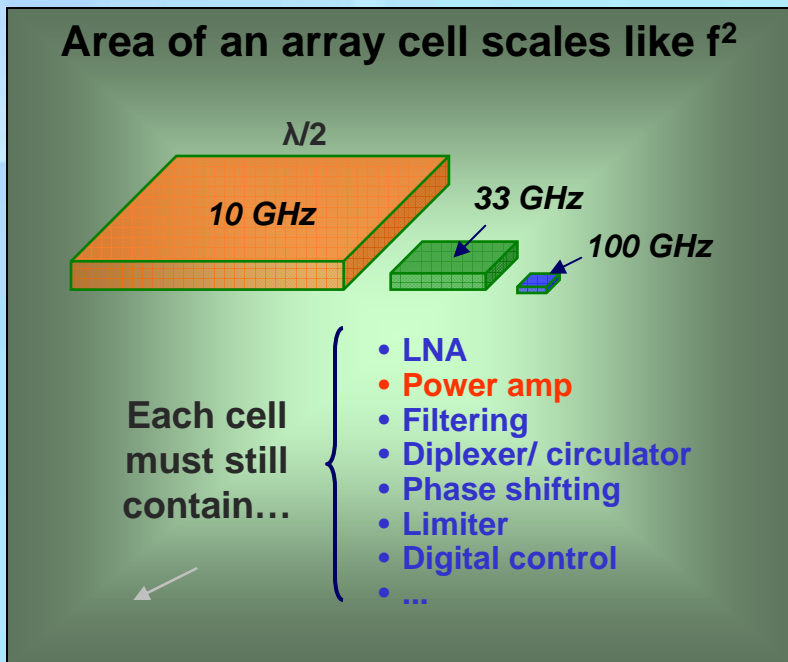
MILCOM



*Arrays are the heart of sensor systems for many military platforms*



# The High Frequency Array



**3D is only way to cram functionality into increasingly smaller pitch**

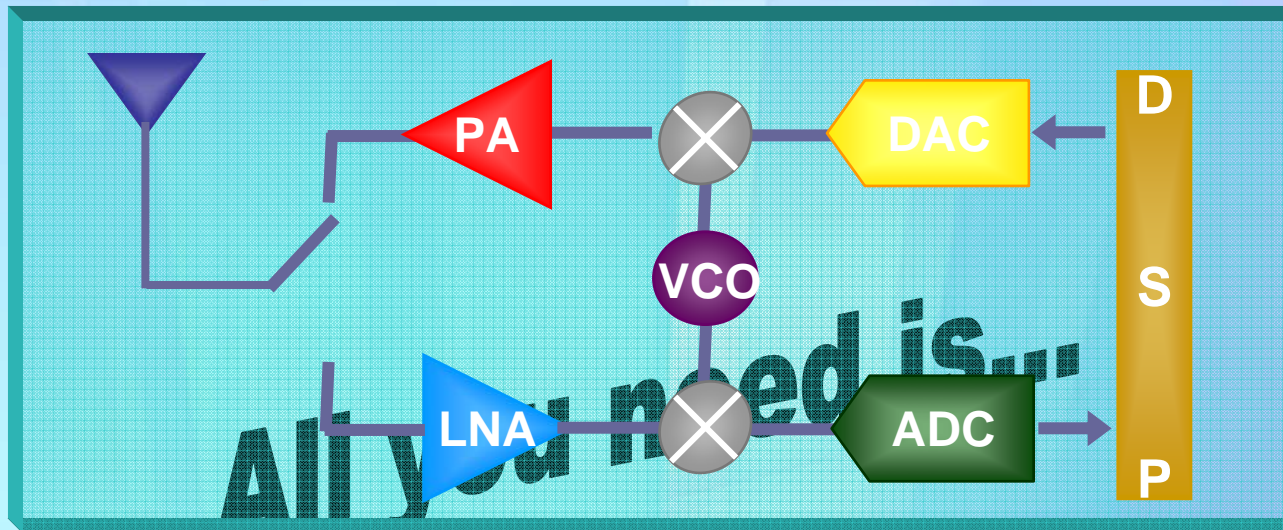




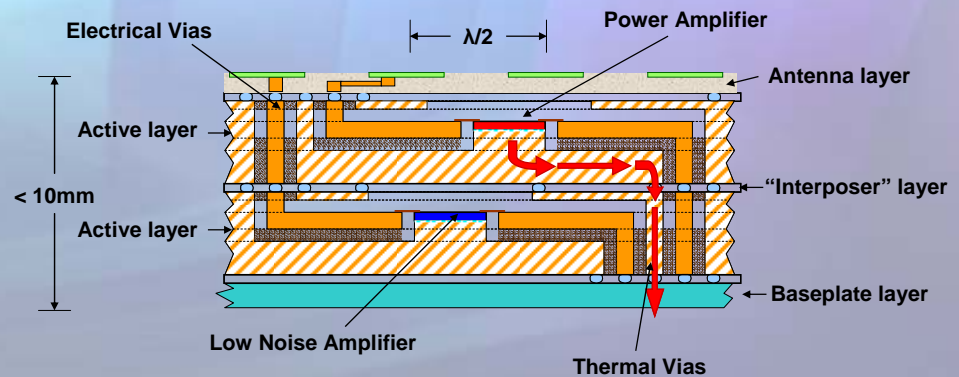
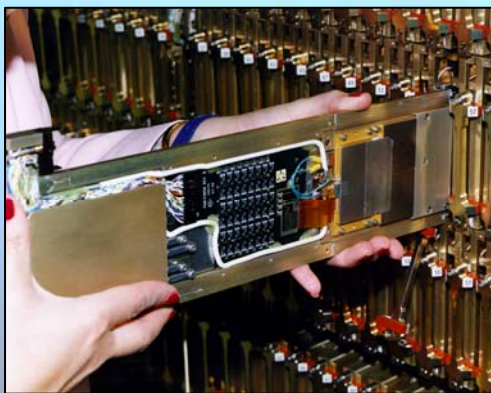
# Challenges for an Ideal Array



## Ideal circuit components



## Ideal integration methods

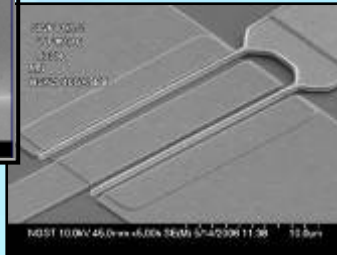
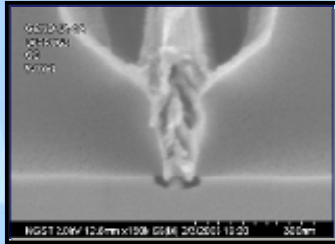




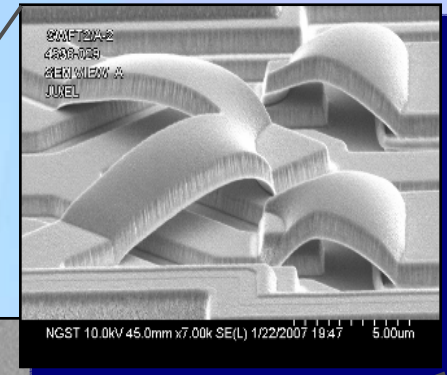
# The High Frequency Integrated Circuit



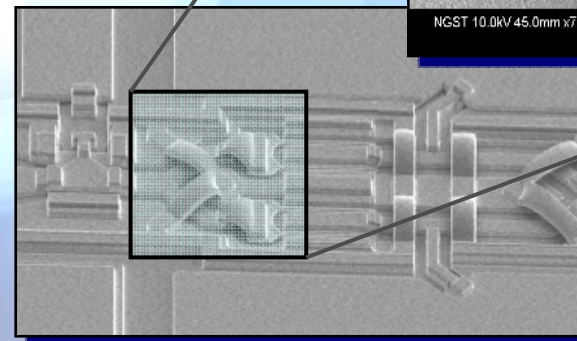
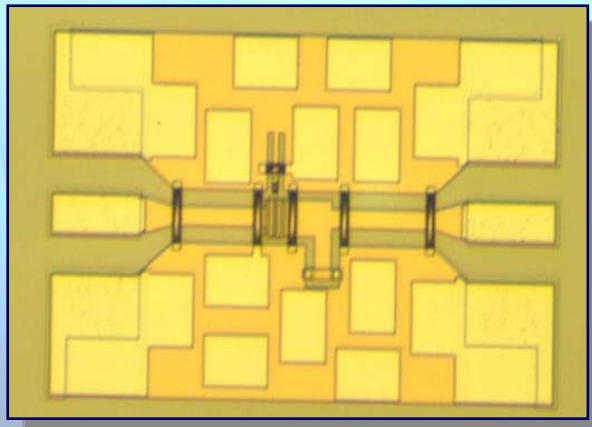
**35nm gate InP HEMT transistor with record  $G_m = 2300\text{mS/mm}$**



**S-MMIC process development**



**347 GHz Integrated Circuit: World's First "s-MMIC"**

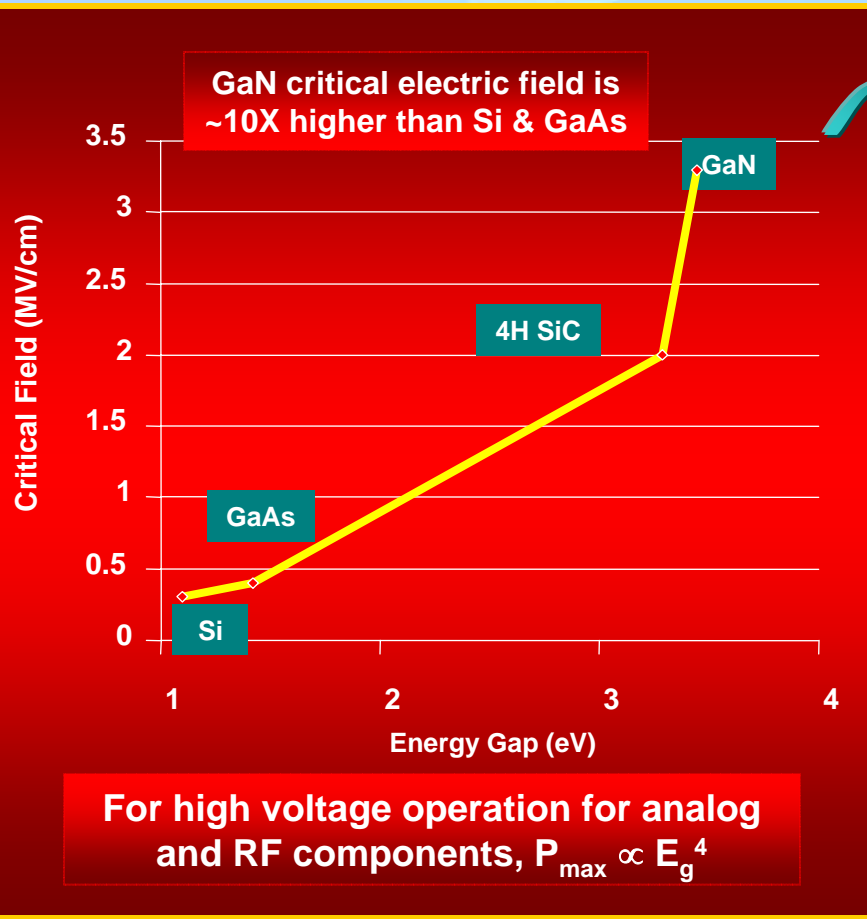


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Space Technology

**THz frequency integrated circuits are becoming a reality**

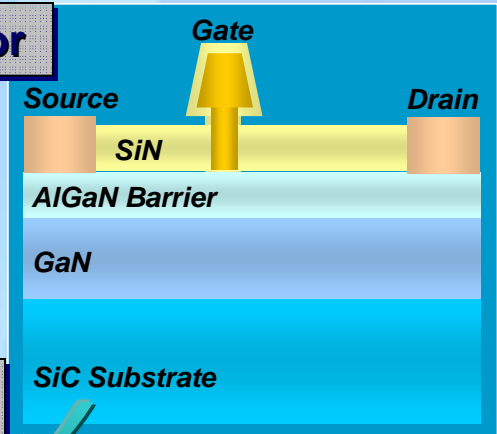


# Wide Bandgap Semiconductors

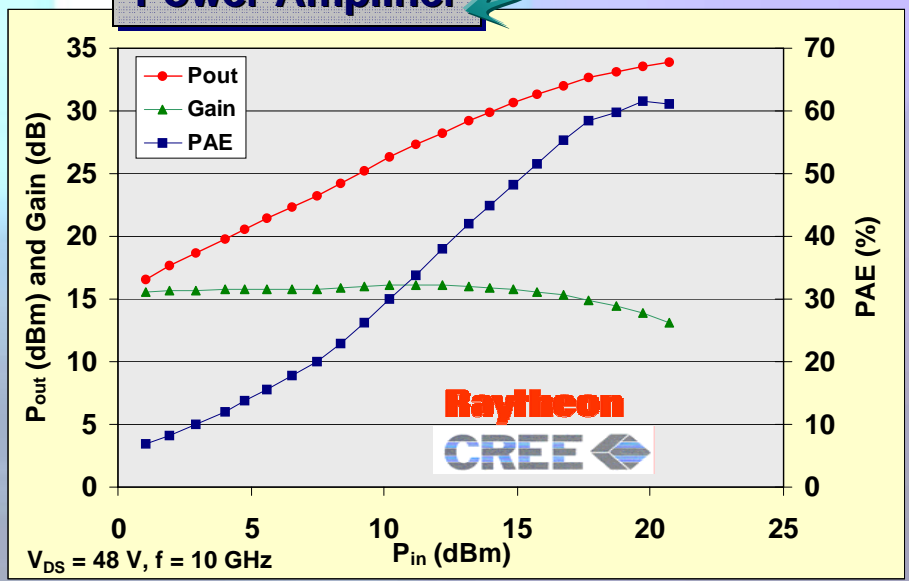


## GaN HEMT Transistor

- Dramatically higher:**
- Output power
  - Efficiency
  - Bandwidth



## GaN HEMT Power Amplifier



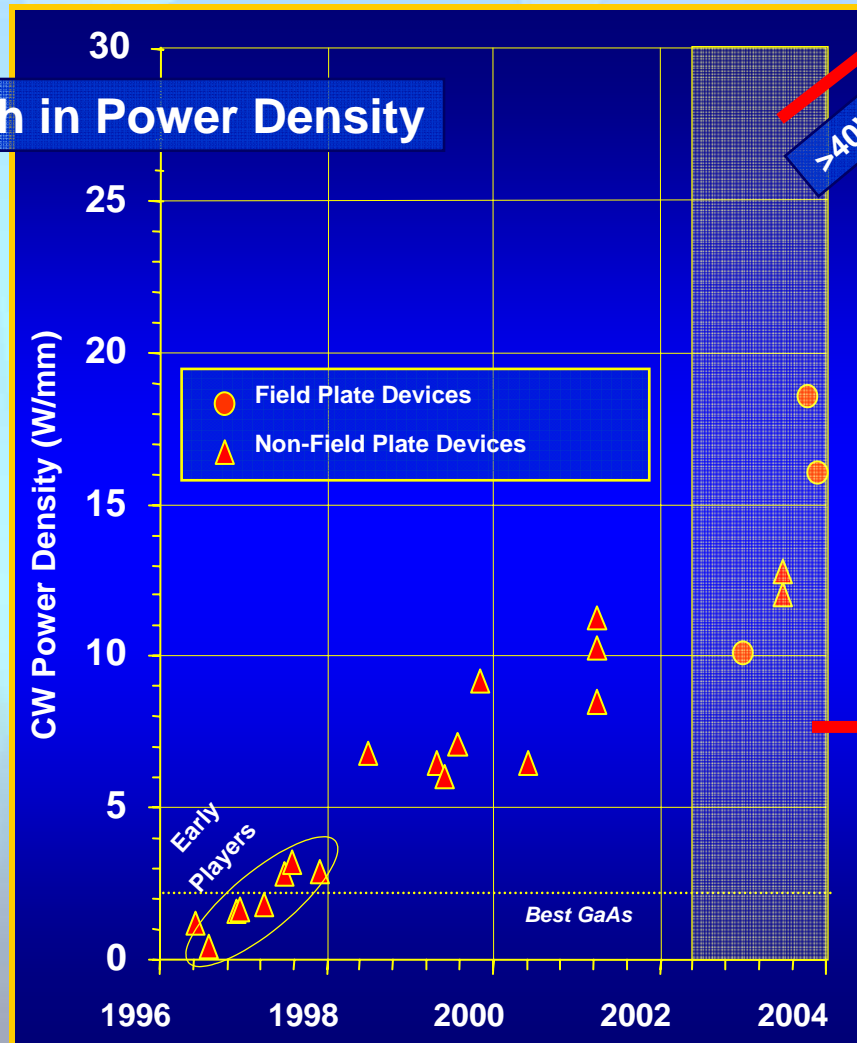
**The ideal array demands the ideal power amplifier transistor material!**



# GaN & Power Density

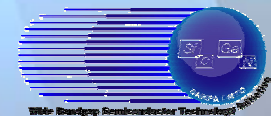


**A Breakthrough in Power Density**



**Small Devices**

**Large Devices**

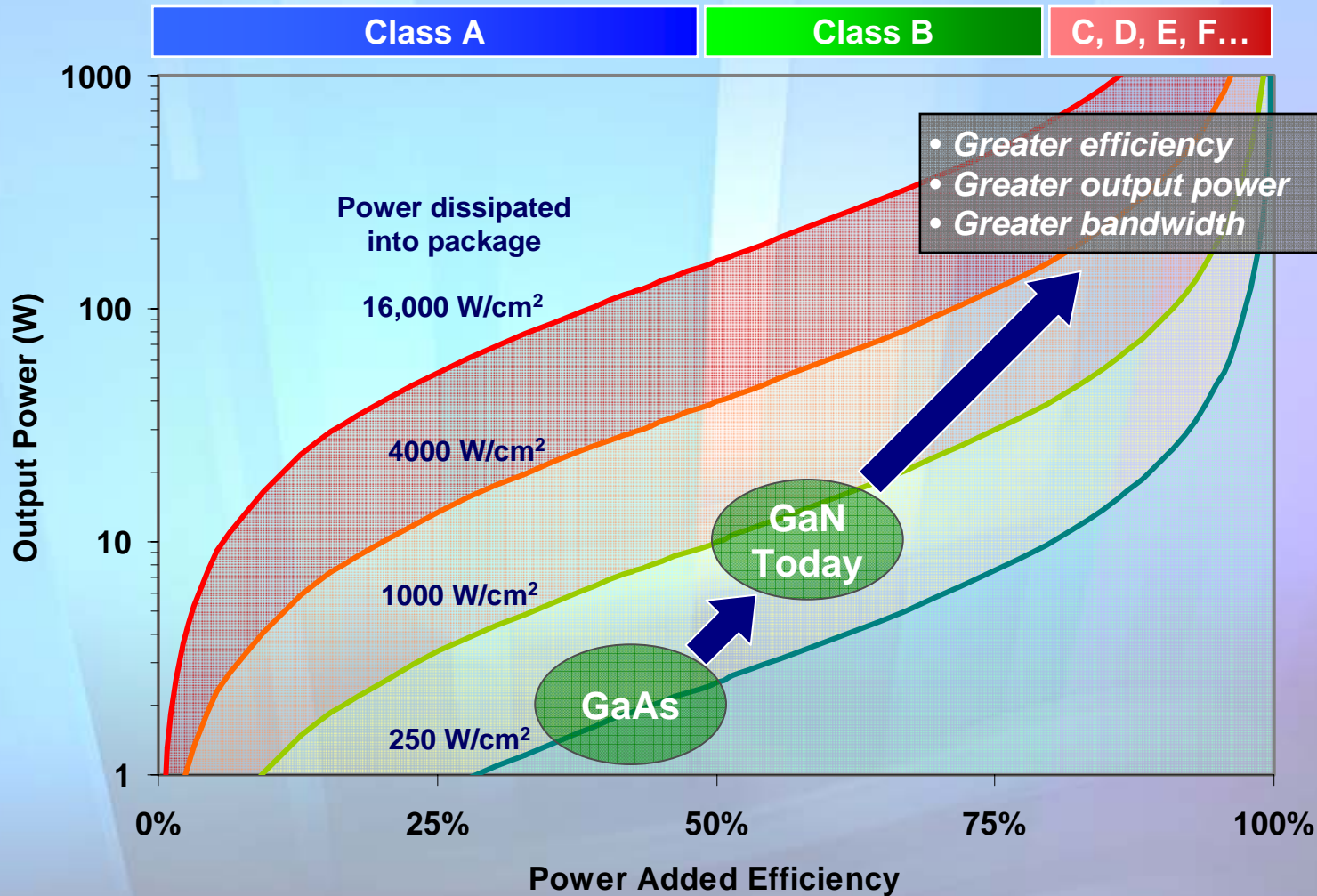


**For large GaN devices, we are still a long way from the material limit**





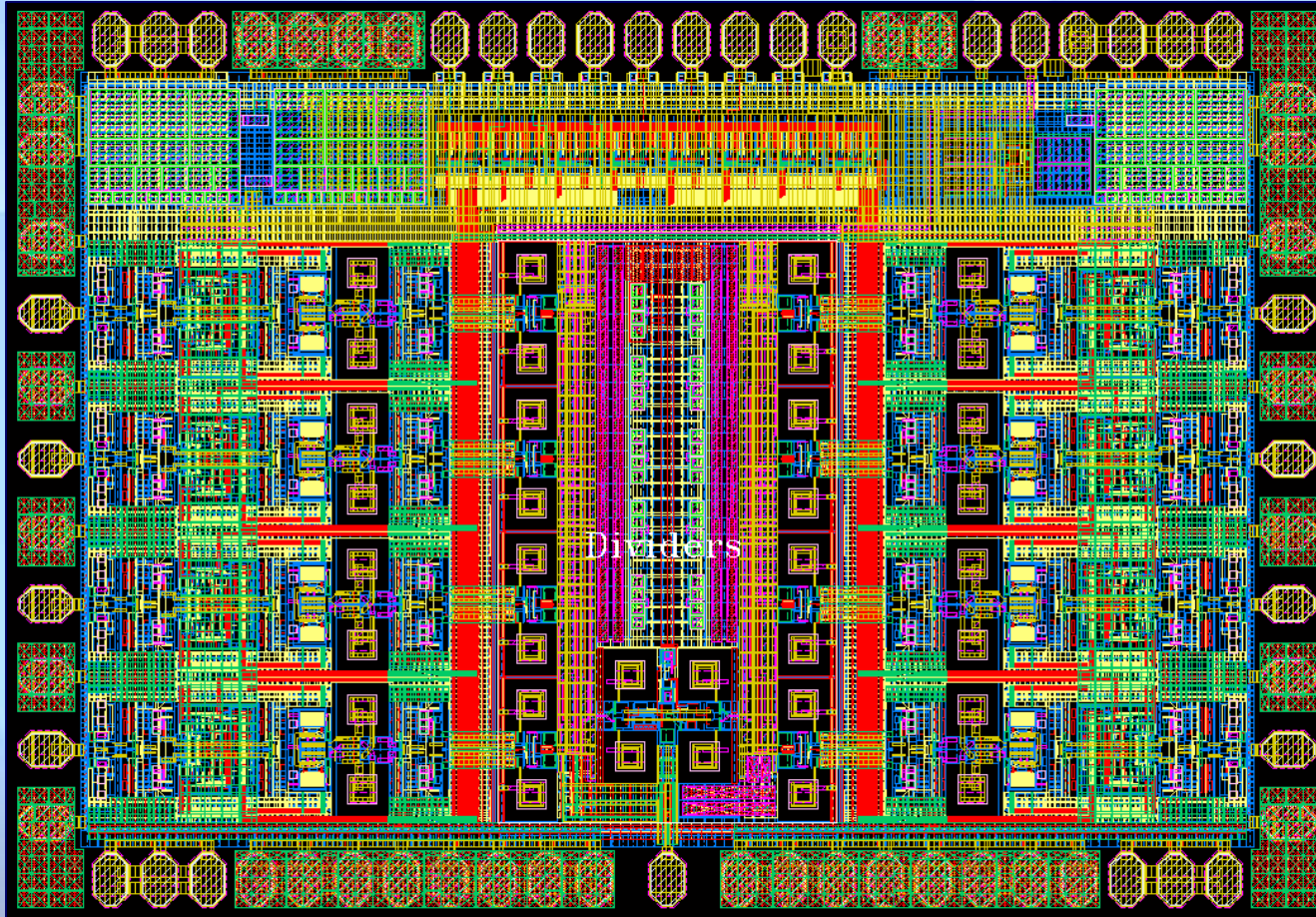
# The Ideal Power Amplifier



*The ideal PA demands a new focus on thermal management*



# Complete Beamformer-on-a-Chip



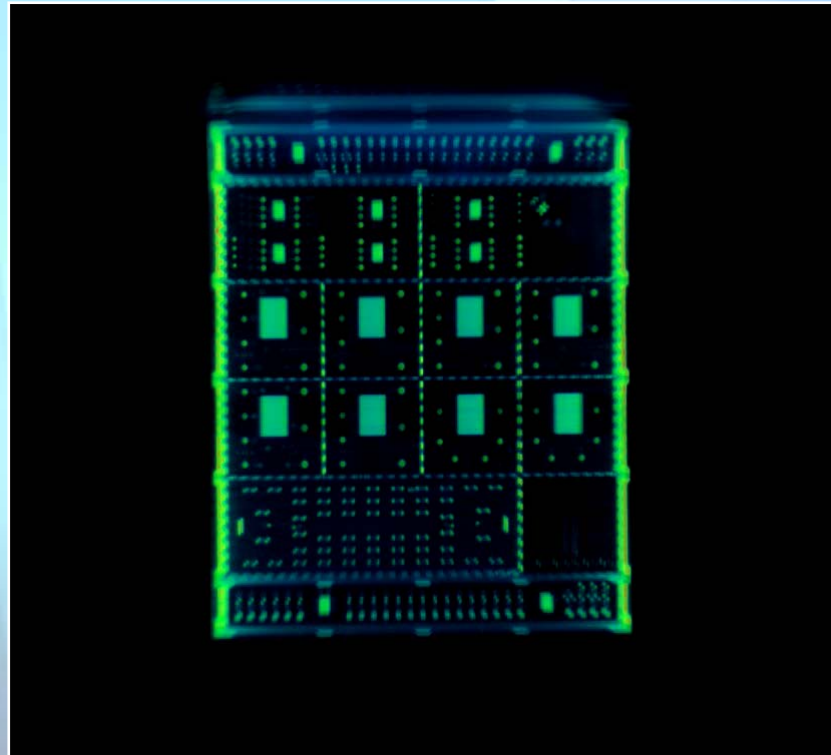
- 44GHz
- 8 channels
- All beamforming functions
  - RF amplifiers
  - 4-bit phase shifters
  - Amplitude controllers
  - Summing network
  - Power control
  - Latches for phase state
  - Address decoders
  - Digital-to-analog converters

→ 2.2x2.4 mm ←





# 3D Integration of an RF Array



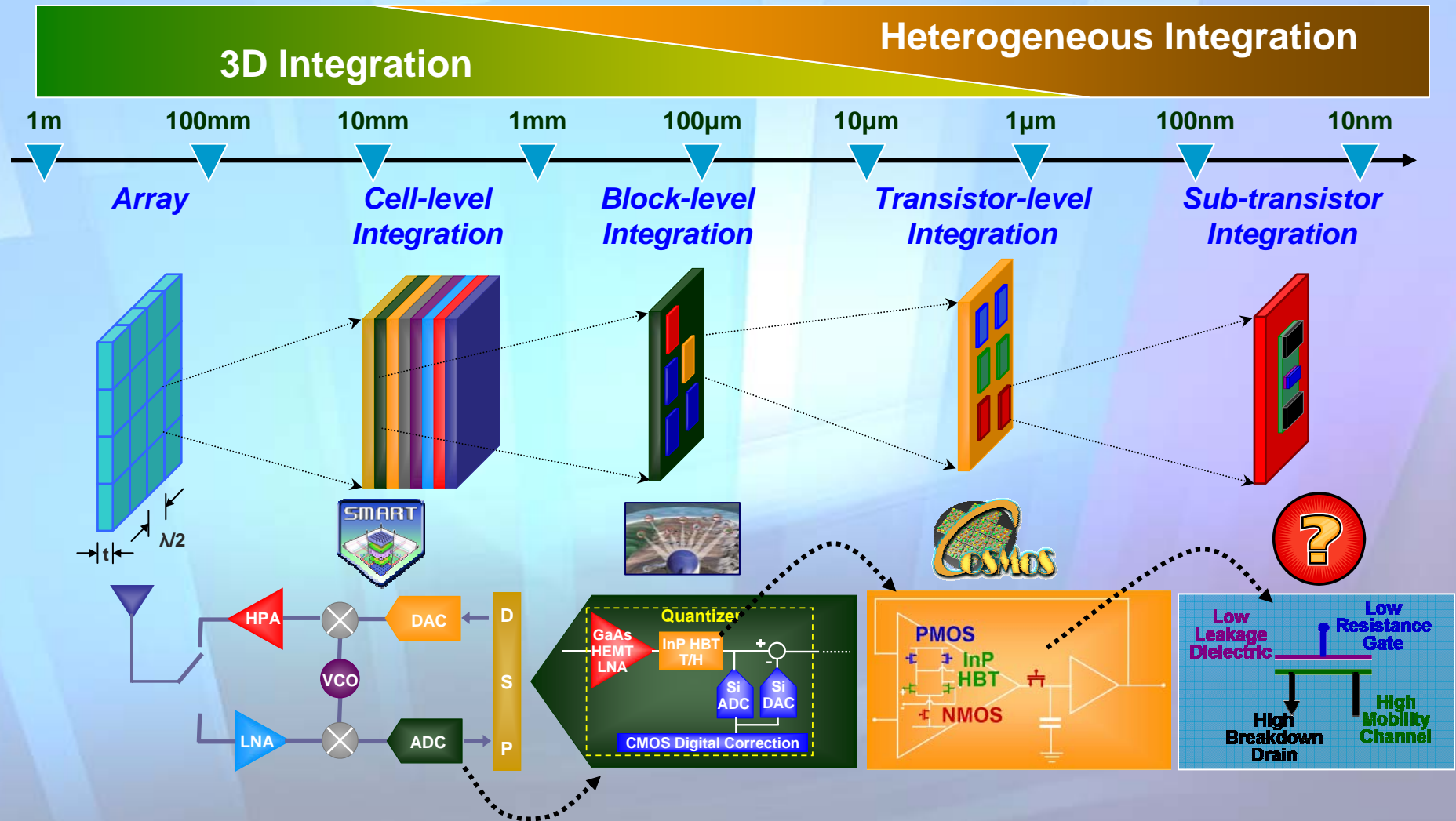
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*Space Technology*

***Today: integrated circuits; Tomorrow: integrated arrays***





# Constructing the Ideal Array



**Integration occurring on all length scales**

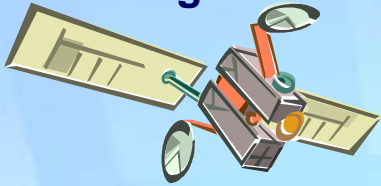




# The Challenge



Range

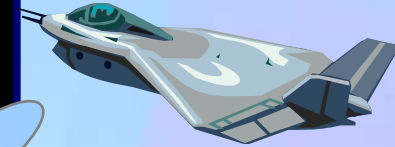


Integrated

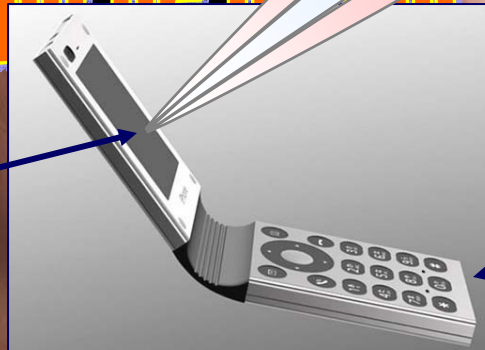
# What could be easier than this?

Massive capacity  
( $>$  coax cable)

Highly directional;  
low probability of intercept



Array no larger  
than display



Highly  
efficient

## Your 200GHz MTO-Phone...

*...made possible by DARPA & the ideal array*